THERMAL CONDUCTIVE MATERIAL AND METHOD FOR PRODUCING THE SAME

ABSTRACT OF THE DISCLOSURE

A thermal conductive material is obtained by kneading an organic material, having the melting point in the range of 30-70℃ and the viscosity at 100℃ equal to or above 70,000cP, and a filler at the ratio of 100:40-900. It has a property of flexibly changing its form by being plasticized due to liquidation of the composing organic material upon receipt of heat from an electronic component. Accordingly, adhesion of the thermal conductive material toward the electronic component and a heat sink is increased and thermal conductivity is improved. Additionally, since the thermal conductive material changes its form according to the outer shape of the electronic component, load is evenly applied to the whole electronic component and does not concentrate on part of the electronic component.